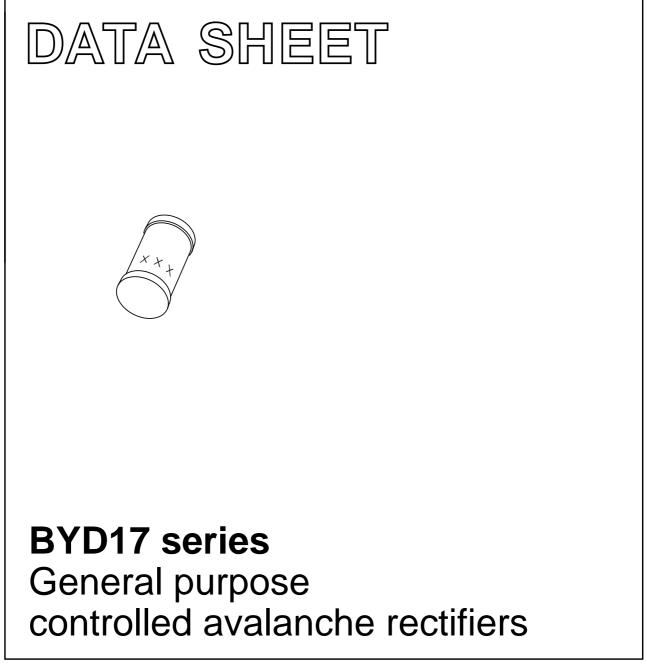
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 1999 Nov 11 2001 Oct 26



General purpose controlled avalanche rectifiers

FEATURES

- · Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Guaranteed avalanche energy absorption capability
- Shipped in 8 mm embossed tape
- Smallest surface mount rectifier outline.

DESCRIPTION

Cavity free cylindrical glass package through Implotec^{TM(1)} technology.

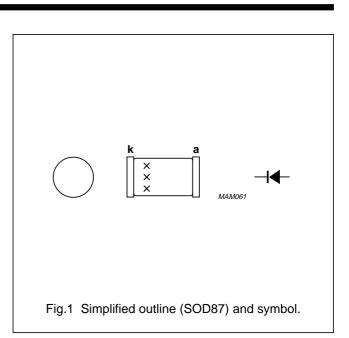
This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.

(1) Implotec is a trademark of Philips.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{RRM}	repetitive peak reverse voltage				
	BYD17D		_	200	V
	BYD17G		_	400	V
	BYD17J		_	600	V
	BYD17K		_	800	V
	BYD17M		_	1000	V
V _{RWM}	crest working reverse voltage				
	BYD17D		_	200	V
	BYD17G		_	400	V
	BYD17J		_	600	V
	BYD17K		-	800	V
	BYD17M		-	1000	V
V _R	continuous reverse voltage				
	BYD17D		_	200	V
	BYD17G		_	400	V
	BYD17J		_	600	V
	BYD17K		_	800	V
	BYD17M		_	1000	V



General purpose controlled avalanche rectifiers

BYD17 series

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{F(AV)}	average forward current	T _{tp} = 105 °C; averaged over any 20 ms period; see Figs 2 and 4	_	1.5	A
		T_{amb} = 65 °C; PCB mounting (see Fig.9); averaged over any 20 ms period; see Figs 3 and 4	_	0.6	A
I _{FSM}	non-repetitive peak forward current	t = 10 ms half sinewave; $T_j = T_{j max}$ prior to surge; $V_R = V_{RRMmax}$	_	20	A
E _{RSM}	non-repetitive peak reverse avalanche energy	L = 120 mH; $T_j = T_{j max}$ prior to surge; inductive load switched off	_	7	mJ
T _{stg}	storage temperature		-65	+175	°C
Tj	junction temperature	see Fig.5	-65	+175	°C

ELECTRICAL CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _F	forward voltage	$I_F = 1 \text{ A}; T_j = T_{j \text{ max}}; \text{see Fig.6}$	_	_	0.93	V
		I _F = 1 A; see Fig.6	_	_	1.05	V
V _{(BR)R}	reverse avalanche breakdown voltage	I _R = 0.1 mA				
	BYD17D		225	_	_	V
	BYD17G		450	_	_	V
	BYD17J		650	_	_	V
	BYD17K		900	_	_	V
	BYD17M		1100	_	-	V
I _R	reverse current	V _R = V _{RRMmax} ; see Fig.7	_	_	1	μA
		$V_R = V_{RRMmax}$; $T_j = 165 \text{ °C}$; see Fig.7	_	_	100	μA
t _{rr}	reverse recovery time	when switched from $I_F = 0.5$ A to $I_R = 1$ A; measured at $I_R = 0.25$ A; see Fig.10	_	3	_	μs
C _d	diode capacitance	$V_R = 0 V$; f = 1 MHz; see Fig.8	_	21	_	pF

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-tp}	thermal resistance from junction to tie-point		30	K/W
R _{th j-a}	thermal resistance from junction to ambient	note 1	150	K/W

Note

1. Device mounted on epoxy-glass printed-circuit board, 1.5 mm thick; thickness of copper ≥40 μm, see Fig.9. For more information please refer to the *"General Part of associated Handbook"*.

General purpose controlled avalanche rectifiers

BYD17 series

GRAPHICAL DATA

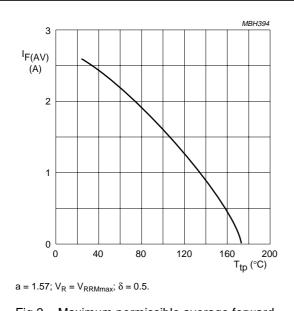


Fig.2 Maximum permissible average forward current as a function of tie-point temperature (including losses due to reverse leakage).

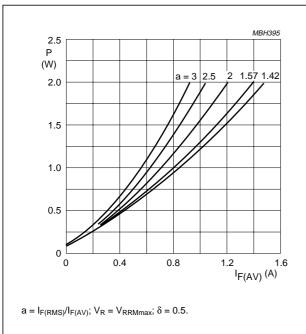


Fig.4 Maximum steady state power dissipation (forward plus leakage current losses, excluding switching losses) as a function of average forward current.

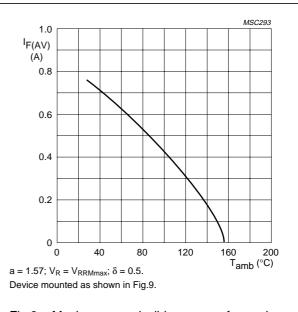
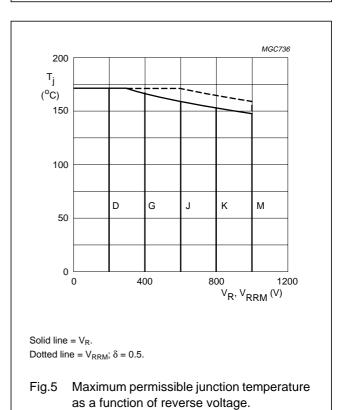
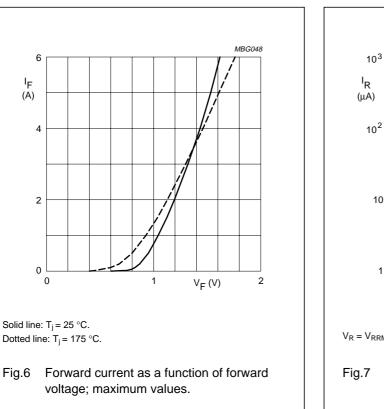


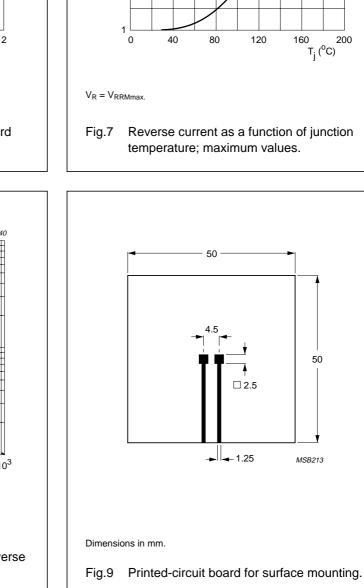
Fig.3 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).

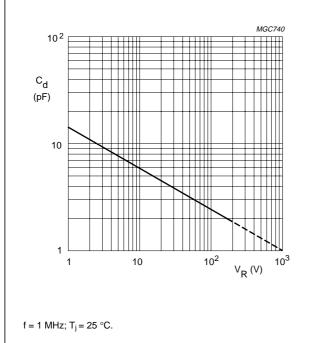


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General purpose controlled avalanche rectifiers

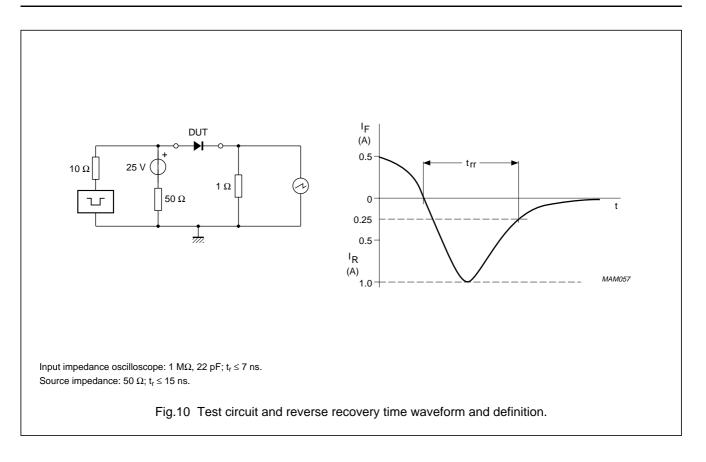






General purpose controlled avalanche rectifiers

BYD17 series



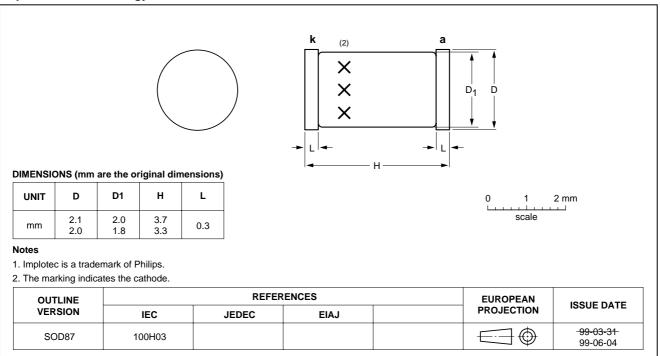
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General purpose controlled avalanche rectifiers

BYD17 series

PACKAGE OUTLINE

Hermetically sealed glass surface mounted package; Implotec^{TM(1)} technology; 2 connectors



Product specification

General purpose controlled avalanche rectifiers

BYD17 series

DATA SHEET STATUS

DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A.

Notes

- 1. Please consult the most recently issued data sheet before initiating or completing a design.
- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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